

TF3004 N-Channel 4 0-V(D-S) MOSFET

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
40V	0.026Ω@10V	5.0A
	0.032Ω@4.5V	

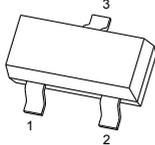
General FEATURE

- TrenchFET Power MOSFET
- Lead free product is acquired
- Surface mount package

APPLICATION

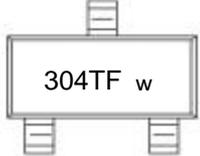
- Load Switch for Portable Devices
- DC/DC Converter

SOT-23



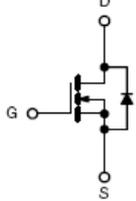
1.GATE
2.SOURCE
3.DRAIN

MARKING



*w: week code

Equivalent Circuit



Absolute Maximum Rating ($T_A=25^{\circ}C$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	40	V
Gate-Source Voltage	V_{GS}	±20	V
Continuous Drain Current	I_D	5	A
Pulsed Drain Current ¹	I_{DM}	19	A
Power Dissipation	P_D	1.2	W
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	°C

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction to Ambient ²	$R_{\theta JA}$	104	°C/W



SHENZHEN TUOFENG SEMICONDUCTOR TECHNOLOGY CO.,LTD
SOT-23 Plastic-Encapsulate MOSFETS

TF3004

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	40	-	-	V
Zero Gate Voltage Drain Current	I_{BSS}	$V_{DS} = 40V, V_{GS} = 0V$	-	-	1	μA
Gate-body Leakage Current	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	± 100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	1	1.6	2	V
Drain-Source On-state Resistance ³	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 5A$	-	26	35	m Ω
		$V_{GS} = 4.5V, I_D = 4A$	-	32	40	
Dynamic Characteristics⁴						
Input Capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = 20V,$ $f = 1MHz$	-	495	-	pF
Output Capacitance	C_{oss}		-	42	-	
Reverse Transfer Capacitance	C_{rss}		-	33	-	
Switching Characteristics⁴						
Total Gate Charge	Q_g	$V_{GS} = 10V, V_{DS} = 20V,$ $I_D = 5A$	-	10	-	nC
Gate-Source Charge	Q_{gs}		-	1.4	-	
Gate-Drain Charge	Q_{gd}		-	1.9	-	
Turn-on Delay Time	$t_{d(on)}$	$V_{GS} = 10V, V_{DD} = 20V,$ $R_G = 3\Omega, I_D = 5A$	-	15	-	ns
Turn-on Rise Time	t_r		-	49.5	-	
Turn-off Delay Time	$t_{d(off)}$		-	19.2	-	
Turn-off Fall Time	t_f		-	11	-	
Source-Drain Diode characteristics						
Body Diode Voltage ³	V_{SD}	$I_S = 1A, V_{GS} = 0V$	-	-	1.2	V
Continuous Source Current	I_S	-	-	-	5	A

Notes:

1. Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}=150^\circ\text{C}$.
2. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
3. Pulse Test: Pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
4. This value is guaranteed by design hence it is not included in the production test.

Typical Characteristics

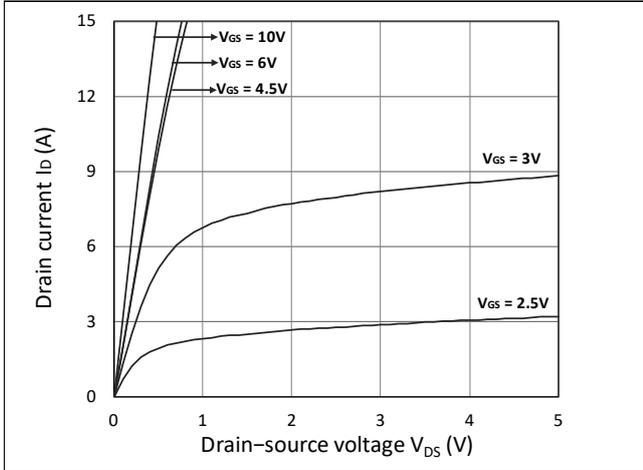


Figure 1. Output Characteristics

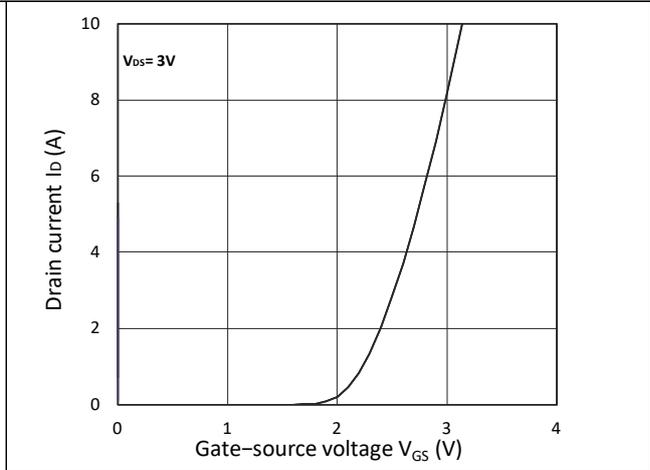


Figure 2. Transfer Characteristics

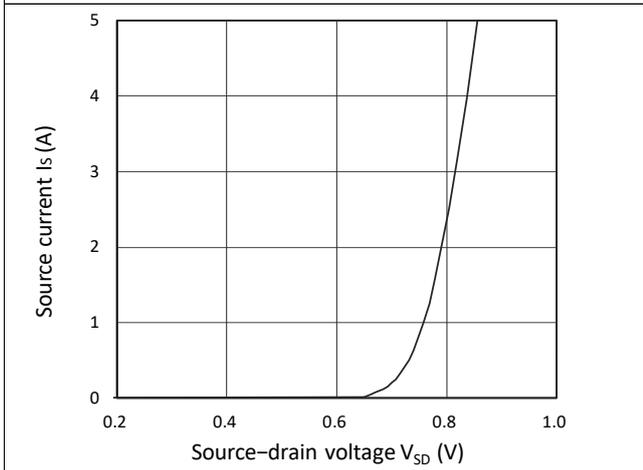


Figure 3. Forward Characteristics of Reverse

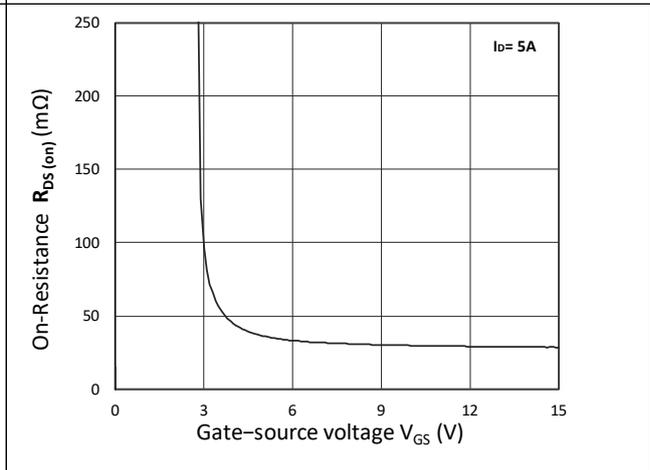


Figure 4. $R_{DS(ON)}$ vs. V_{GS}

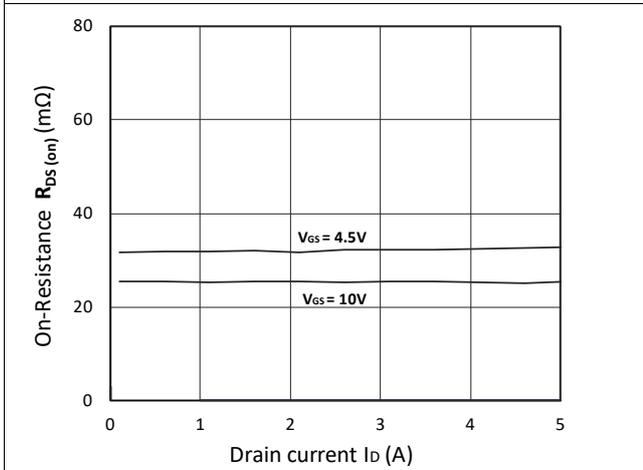


Figure 5. $R_{DS(ON)}$ vs. I_D

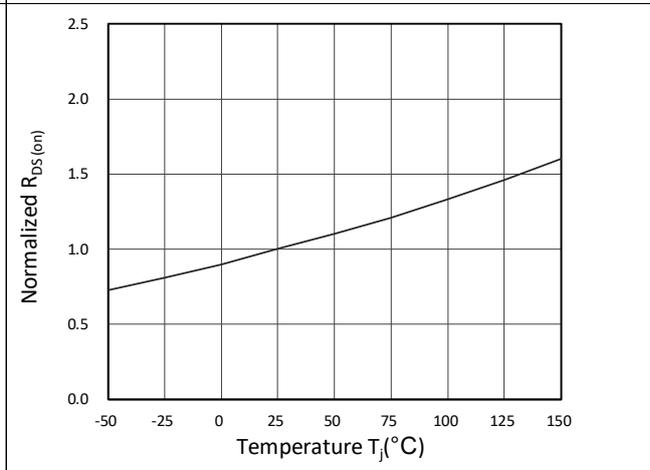


Figure 6. Normalized $R_{DS(ON)}$ vs. Temperature

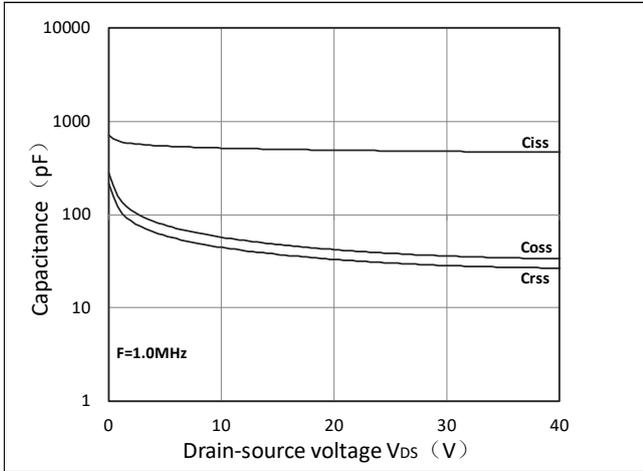


Figure 7. Capacitance Characteristics

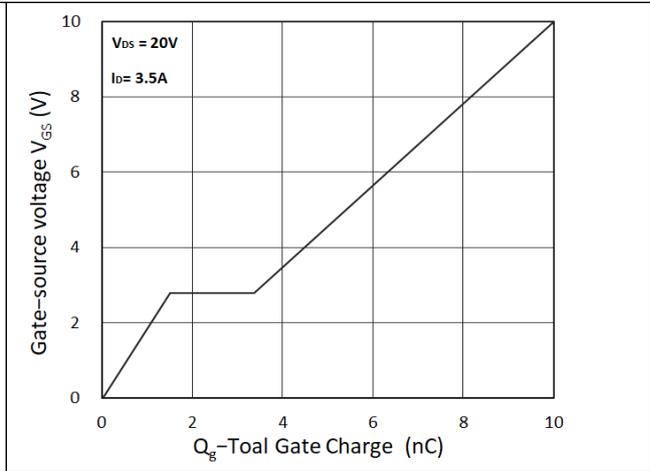
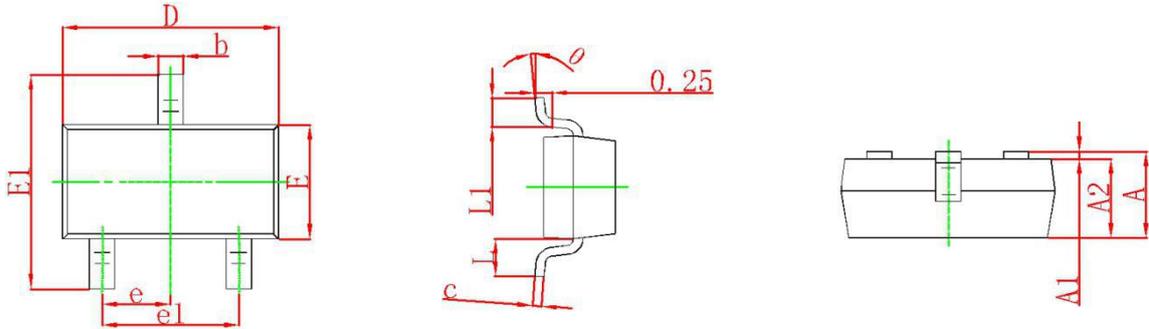


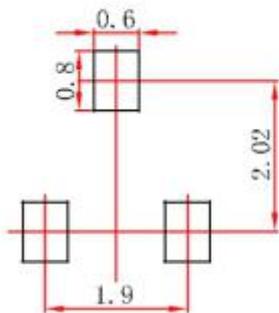
Figure 8. Gate Charge Characteristics

SOT-23 Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF		0.022 REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

SOT-23 Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: $\pm 0.05\text{mm}$.
3. The pad layout is for reference purposes only.